

STARPOWER

SEMICONDUCTOR

MOSFET

MD75FSC120L3SF

1200V/75A 6 in one-package

General Description

STARPOWER MOSFET Power Module provides very low $R_{DS(on)}$ as well as optimized intrinsic diode. It's designed for the applications such SMPS and solar power.

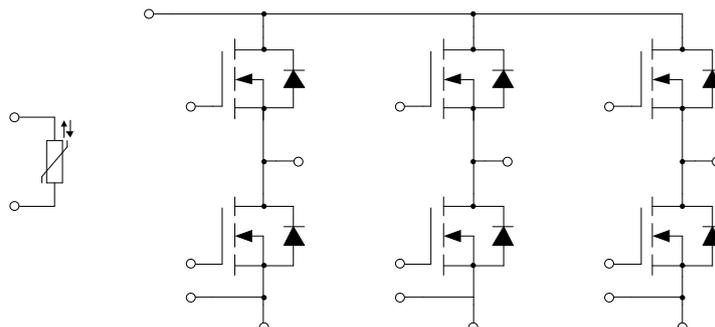
Features

- SiC power MOSFET
- Low $R_{DS(on)}$
- Optimized intrinsic reverse diode
- Avalanche ruggedness
- Low inductance case
- substrate for low thermal resistance
- Isolated heatsink using DBC technology
- PressFIT contact technology

Typical Applications

- Uninterruptible power supply
- Solar Power
- Switching mode power supply

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**MOSFET**

Symbol	Description	Value	Unit
V_{DSS}	Drain-Source Voltage	1200	V
V_{GSSmax}	Gate-Source Voltage	-8/+19	V
V_{GSSop}	Gate-Source Voltage	-4/+15	V
I_D	Drain Current @ $T_C=25^{\circ}\text{C}$	95	A
	@ $T_C=80^{\circ}\text{C}$	75	A
I_{DM}	Pulsed Drain Current	250	A
P_D	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	277	W

Inverse Diode

Symbol	Description	Value	Unit
I_S	Source Current @ $T_C=100^{\circ}\text{C}$	34	A
I_{SM}	Pulsed Source Current	250	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^{\circ}\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V

MOSFET Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source On-Resistance	$I_D=75\text{A}, V_{GS}=15\text{V}, T_j=25^\circ\text{C}$		16.0	20.8	$\text{m}\Omega$
		$I_D=75\text{A}, V_{GS}=15\text{V}, T_j=175^\circ\text{C}$		25.6		
$V_{GS(th)}$	Gate-Source Threshold Voltage	$I_D=23.0\text{mA}, V_{DS}=V_{GS}, T_j=25^\circ\text{C}$	1.8	2.5	3.6	V
		$I_D=23.0\text{mA}, V_{DS}=V_{GS}, T_j=175^\circ\text{C}$		2.0		
g_{fs}	Forward Transconductance	$V_{DS}=20\text{V}, I_D=75\text{A}, T_j=25^\circ\text{C}$		58.0		S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$			32	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=V_{GSS}, V_{DS}=0\text{V}, T_j=25^\circ\text{C}$			250	nA
R_{Gint}	Internal Gate Resistance			2.6		Ω
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=1000\text{V}, f=1.0\text{MHz}$		5.78		nF
C_{oss}	Output Capacitance			0.23		nF
C_{rss}	Reverse Transfer Capacitance			0.01		nF
Q_g	Total Gate Charge	$I_D=75\text{A}, V_{DS}=800\text{V}, V_{GS}=-4/+15\text{V}$		227		nC
Q_{gs}	Gate-Source Charge			64		nC
Q_{gd}	Gate-Drain ("Miller") Charge			77		nC

Inverse Diode Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_S=37.5\text{A}, V_{GS}=-4\text{V}, T_j=25^\circ\text{C}$		4.60		V
		$I_S=37.5\text{A}, V_{GS}=-4\text{V}, T_j=175^\circ\text{C}$		4.20		V
t_{rr}	Diode Reverse Recovery Time	$V_R=800\text{V}, I_S=75\text{A}, di/dt=4720\text{A}/\mu\text{s}, V_{GS}=-4\text{V}, T_j=150^\circ\text{C}$		48		ns
Q_r	Diode Reverse Recovery Charge			1200		nC
I_{rm}	Peak Reverse Recovery Current			59.0		A

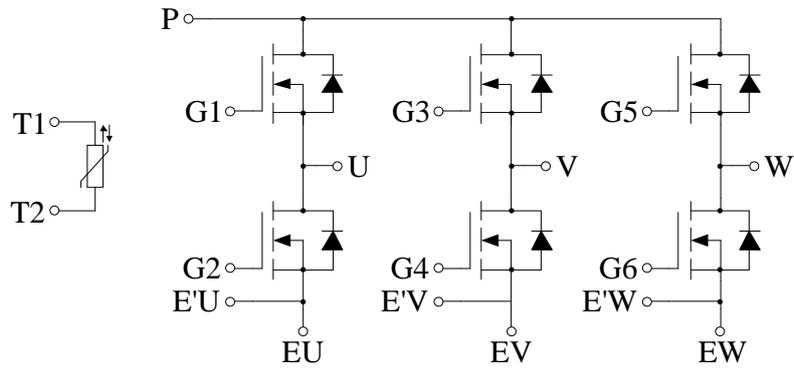
NTC Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of R_{100}	$T_C=100^{\circ}\text{C}, R_{100}=493.3\Omega$	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K
$B_{25/80}$	B-value	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15\text{K}))]$		3411		K
$B_{25/100}$	B-value	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15\text{K}))]$		3433		K

Module Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

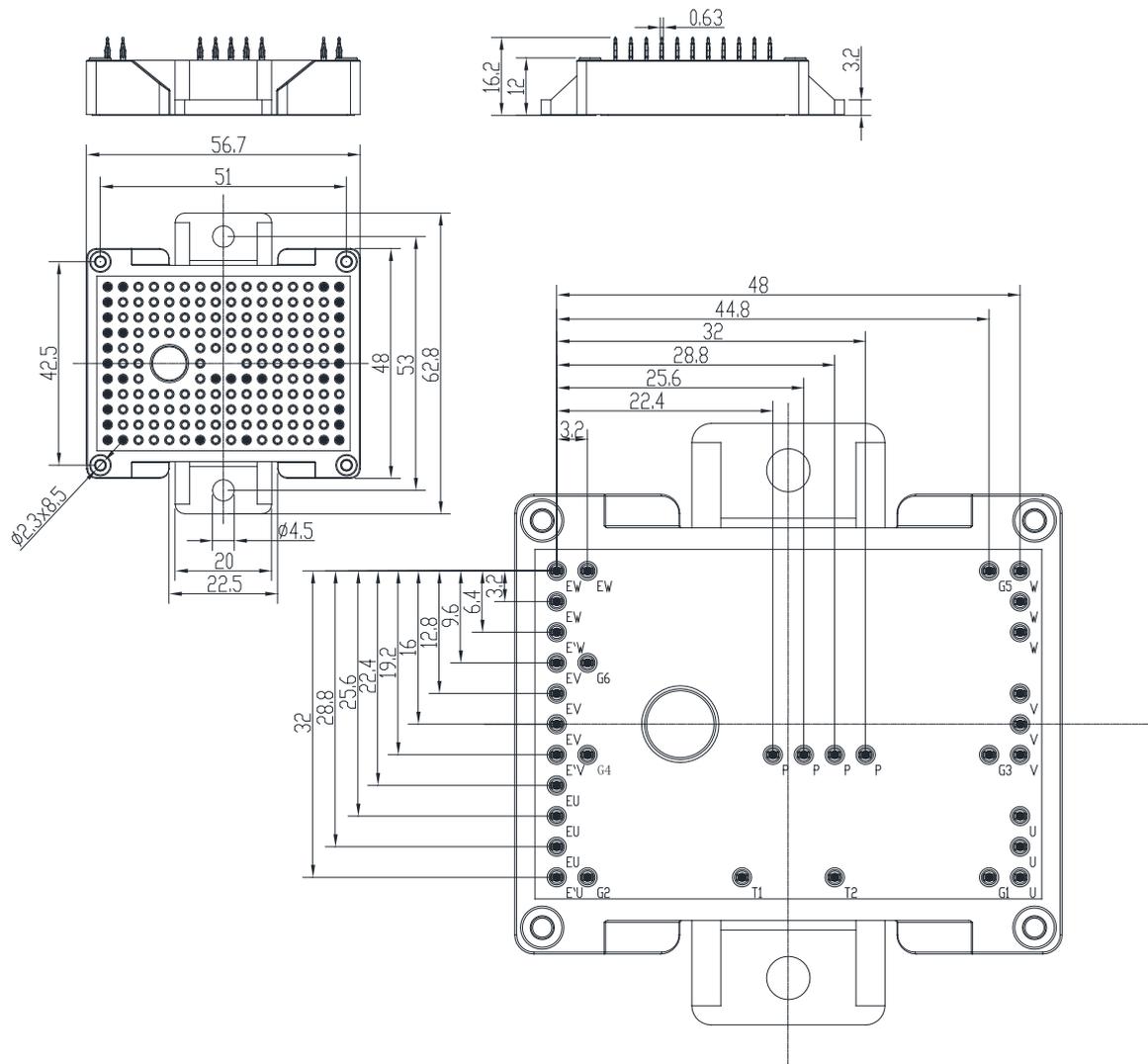
Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thC}	Junction-to-Case (per MOSFET)		0.491	0.540	K/W
R_{thCH}	Case-to-Heatsink (per MOSFET) Case-to-Heatsink (per Module)		0.222 0.037		K/W
F	Mounting Force Per Clamp	40		80	N
G	Weight of Module		39		g

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



Terms and Conditions of Usage

The data contained in this product datasheet is exclusively intended for technically trained staff. you and your technical departments will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to such application.

This product data sheet is describing the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively pursuant the terms and conditions of the supply agreement. There will be no guarantee of any kind for the product and its characteristics.

Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you (see www.powersemi.cc), For those that are specifically interested we may provide application notes.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the Product in aviation applications, in health or live endangering or life support applications, please notify.

If and to the extent necessary, please forward equivalent notices to your customers.
Changes of this product data sheet are reserved.